

LN352GPX

Square Type

□ 4.0 mm × 4.0 mm

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation | P_D | 90 | mW |
| Forward current | I_F | 30 | mA |
| Pulse forward current * | I_{FP} | 150 | mA |
| Reverse voltage | V_R | 4 | V |
| Operating ambient temperature | T_{opr} | -25 to +85 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -30 to +100 | $^\circ\text{C}$ |

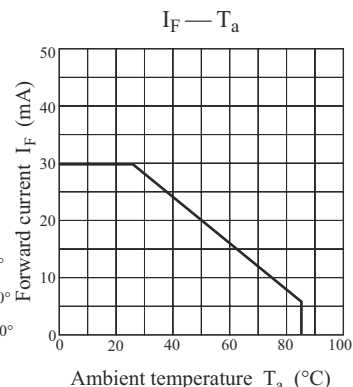
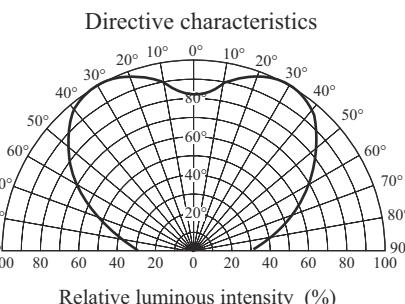
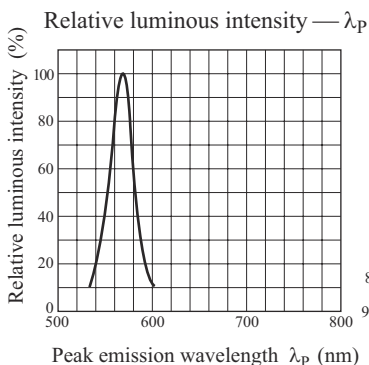
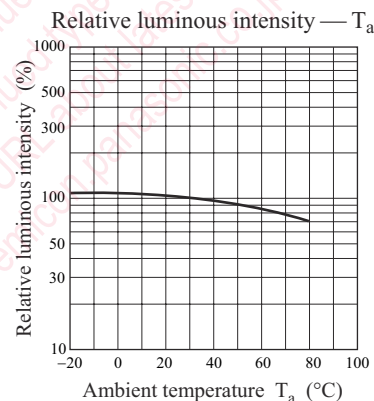
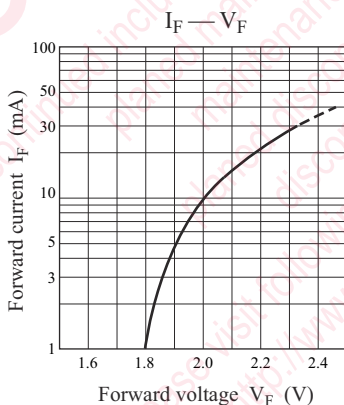
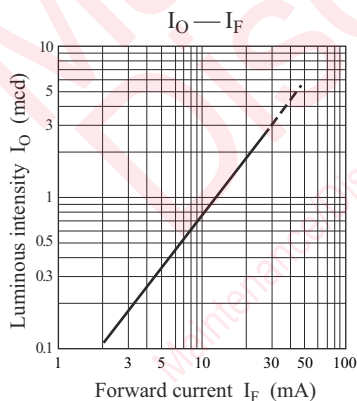
■ Lighting Color

- Yellow Green

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

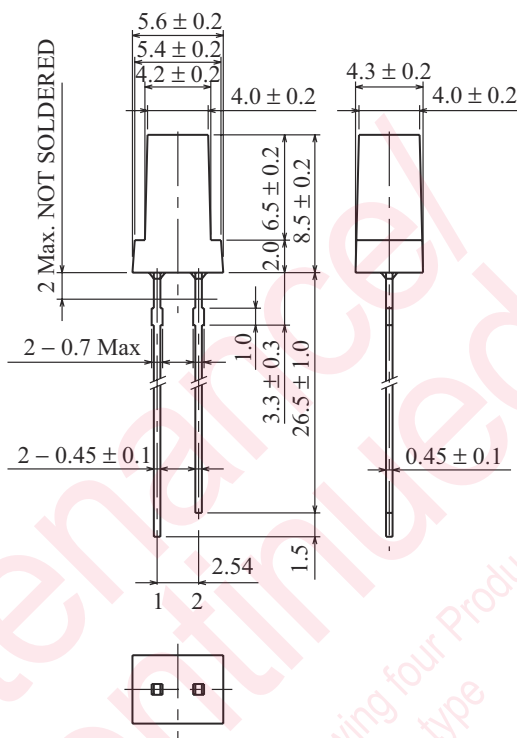
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--------------------------|-----------------|----------------------|-----|-----|-----|---------------|
| Luminous intensity | I_O | | 0.7 | 2.0 | | mcd |
| Reverse current | I_R | $V_R = 4\text{ V}$ | | | 10 | μA |
| Forward voltage | V_F | $I_F = 20\text{ mA}$ | | 2.2 | 2.8 | V |
| Peak emission wavelength | λ_p | $I_F = 20\text{ mA}$ | | 565 | | nm |
| Spectral half band width | $\Delta\lambda$ | $I_F = 20\text{ mA}$ | | 30 | | nm |



■ Package (Unit: mm)

LLXFTN2SK520



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued includes following four Product lifecycle stage.
planned maintenance type
maintenance type
planned discontinued type
discontinued type
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